



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-03-15
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HZC4*UT85AA6	A	SHENZHEN B/E	2018-03-15
Amount	UoM	Unit type	ST ECOPACK Grade	
331.30	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	6.4-6-2.2	5	S BAND	

Comment	C4 PPACK 5 LEADS; MDF valid for LD39150PT-R			
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QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZC4*UT85AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.232	mg	supplier	die	Silicon (Si)	7440-21-3		3.129	mg	968131	9445
				supplier	metallization	Aluminium (Al)	7429-90-5		0.040	mg	12376	121
				supplier	Passivation	Silicon Nitride	12033-89-5		0.014	mg	4332	42
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	5879	57
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	619	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1856	18
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.022	mg	6807	66
Leadframe	Copper & its alloys	159.487	mg	supplier	alloy	Copper (Cu)	7440-50-8		158.658	mg	994802	478895
				supplier	alloy	Iron (Fe)	7439-89-6		0.159	mg	997	480
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	301	145
				supplier	metallization	Nickel (Ni)	7440-02-0		0.618	mg	3875	1865
				supplier	metallization	Phosphorus (P)	12185-10-3		0.004	mg	25	12
Soft solder	Solder	3.199	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	3.055	mg	954986	9221
				supplier	solder	Silver (Ag)	7440-22-4		0.080	mg	25008	241
				supplier	solder	Tin (Sn)	7440-31-5		0.064	mg	20006	193
				supplier	wire	Copper (Cu)	7440-50-8		0.036	mg	1000000	109
Encapsulation	Other Organic Materials	164.765	mg	supplier	mold compound	Silica, vitreous	60676-86-0		144.169	mg	874998	435161
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		6.591	mg	40002	19894
				supplier	mold compound	Epoxy Resin	25068-38-6		4.943	mg	30000	14920
				supplier	mold compound	phenol resin	29690-82-2		8.238	mg	49998	24866
				supplier	mold compound	Carbon black	1333-86-4		0.824	mg	5001	2487
Connections coating	Solder	0.582	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.582	mg	1000000	1757